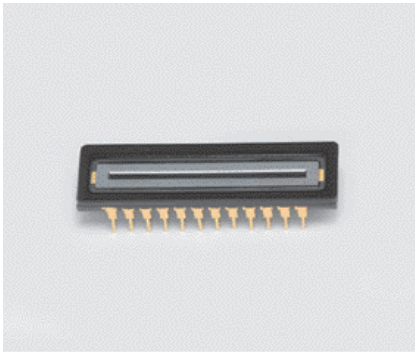


CCD linear image sensors

S11155-2048 S11156-2048



Back-thinned CCD image sensors with electronic shutter function

The S11155-2048 and S11156-2048 are back-thinned CCD linear image sensors with an internal electronic shutter for spectrometers. These image sensors use a resistive gate structure that allows high-speed transfer. Each pixel has a lengthwise size needed by spectrometers but ensures readout with low image lag.

Features

- **Built-in electronic shutter**
- **Minimum integration time: 30 μs**
- **High sensitivity from the ultraviolet region (spectral response range: 200 to 1100 nm)**
- **Readout speed: 10 MHz max.**
- **Image lag: 0.1% typ.**

Applications

- **Spectrometers**
- **Image readout**

General ratings

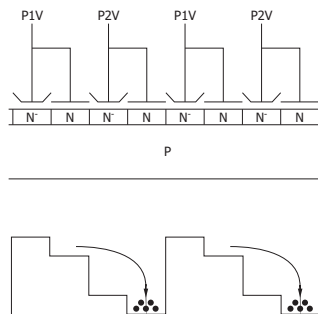
Parameter	S11155-2048	S11156-2048
Pixel size	14 (H) × 500 (V) μm	14 (H) × 1000 (V) μm
Number of total pixels	2068 (H) × 1 (V)	
Number of active pixels	2048 (H) × 1 (V)	
Active area	28.672 (H) × 0.500 (V) mm	28.672 (H) × 1.000 (V) mm
Horizontal clock phase	2-phase	
Output circuit	Two-stage MOSFET source follower	
Package	24-pin ceramic DIP (refer to dimensional outline)	
Window*1	Quartz glass	

*1: Temporary window type (ex. S11155-2048N) is available upon request.

Resistive gate structure

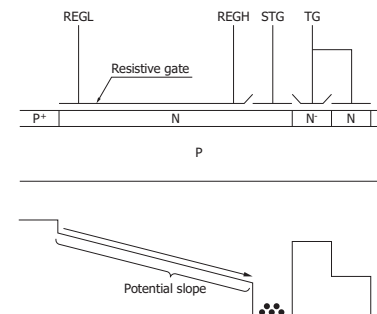
In ordinary CCDs, one pixel contains multiple electrodes and a signal charge is transferred by applying different clock pulses to those electrodes [Figure 1]. In resistive gate structures, a single high-resistance electrode is formed in the active area, and a signal charge is transferred by means of a potential slope that is created by applying different voltages across the electrode [Figure 2]. Compared to a CCD area image sensor which is used as a linear sensor by line binning, a one-dimensional CCD having a resistive gate structure in the active area offers higher speed transfer, allowing readout with low image lag even if the pixel height is large.

[Figure 1] Schematic diagram and potential of ordinary 2-phase CCD



KMPDC0320EA

[Figure 2] Schematic diagram and potential of resistive gate structure



KMPDC0321EB

▣ Absolute maximum ratings (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	
Operating temperature*2 *3	Topr	-50	-	+50	°C	
Storage temperature	Tstg	-50	-	+70	°C	
OD voltage	VOD	-0.5	-	+25	V	
RD voltage	VRD	-0.5	-	+18	V	
Vret voltage	Vret	-0.5	-	+18	V	
ARD voltage	VARD	-0.5	-	+18	V	
ISH voltage	VISH	-0.5	-	+18	V	
ARG voltage	VARG	-10	-	+15	V	
STG voltage	VSTG	-10	-	+15	V	
IGH voltage	VIG1H, VIG2H	-10	-	+15	V	
SG voltage	VSG	-10	-	+15	V	
OG voltage	VOG	-10	-	+15	V	
RG voltage	VRG	-10	-	+15	V	
TG voltage	VTG	-10	-	+15	V	
Resistive gate voltage	High	VREGH	-10	-	+15	V
	Low	VREGL				
Horizontal clock voltage	VP1H, VP2H	-10	-	+15	V	

*2: Chip temperature

*3: The chip temperature may increase due to heating in high-speed operation. We recommend taking measures to dissipate heat as needed. For more details, refer to the technical information.

▣ Operating conditions (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	
Output transistor drain voltage	VOD	12	15	18	V	
Reset drain voltage	VRD	14	15	16	V	
All reset drain voltage	VARD	11	12	13	V	
All reset gate voltage	High*4	VARGH	7	8	9	V
	Low*5	VARGL	-2	-1.5	-1	
Output gate voltage	VOG	4.5	5	5.5	V	
Storage gate voltage	VSTG	-	0	-	V	
Substrate voltage	VSS	-	0	-	V	
Resistive gate high voltage	High	VREGHH	-3.5	-3	-2.5	V
	Low	VREGHL	-9	-8	-7	
Resistive gate low voltage	High	VREGLH	-	VREGHH - 2.5	-	V
	Low	VREGLL	-9	-8	-7	
Output amplifier return voltage	Vret	-	1	2	V	
Test point	Horizontal input source	VISH	-	VRD	-	V
	Horizontal input gate	VIG1H, VIG2H	-9	-8	-	V
Horizontal shift register clock voltage	High	VP1HH, VP2HH	5	6	7	V
	Low	VP1HL, VP2HL	-6	-5	-4	
Summing gate voltage	High	VSGH	5	6	7	V
	Low	VSGL	-6	-5	-4	
Reset gate voltage	High	VRGH	7	8	9	V
	Low	VRGL	-6	-5	-4	
Transfer gate voltage	High	VTGH	8.5	9	9.5	V
	Low	VTGL	-7.5	-7	-6.5	
External load resistance	RL	2.0	2.2	2.4	kΩ	

*4: All reset on

*5: All reset off

■ Electrical characteristics (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	
Signal output frequency	fc	-	5	10	MHz	
Line rate	LR	-	2	4	kHz	
Horizontal shift register capacitance	CP1H, CP2H	-	200	-	pF	
All reset gate capacitance	CARG	-	100	-	pF	
Resistive gate capacitance	S11155-2048	-	1000	-	pF	
	S11156-2048	-	2000	-		
Summing gate capacitance	CSG	-	10	-	pF	
Reset gate capacitance	CRG	-	10	-	pF	
Transfer gate capacitance	CTG	-	100	-	pF	
Charge transfer efficiency*6	CTE	0.99995	0.99999	-	-	
DC output level	Vout	7	8	9	V	
Output impedance	Zo	-	300	-	Ω	
Output amplifier return current	Iret	-	0.4	-	mA	
Power consumption	S11155-2048	PAMP*7	-	75	-	mW
		PREG*8	1.4	2.5	12.5	
	S11156-2048	PAMP*7	-	75	-	
		PREG*8	0.7	1.3	6.3	
Resistive gate resistance*9	S11155-2048	RREG	0.5	2.5	4.5	kΩ
	S11156-2048		1	5	9	

*6: Charge transfer efficiency per pixel of CCD shift register, measured at half of the full well capacity

*7: Power consumption of the on-chip amplifier plus load resistance

*8: Power consumption at REG

*9: Resistance value between REGH and REGL

■ Electrical and optical characteristics (Ta=25 °C, unless otherwise noted)

Parameter	Symbol	S11155-2048			S11156-2048			Unit	
		Min.	Typ.	Max.	Min.	Typ.	Max.		
Saturation output voltage	Vsat	-	Fw x Sv	-	-	Fw x Sv	-	V	
Full well capacity	Fw	-	200	-	-	200	-	ke ⁻	
CCD node sensitivity	Sv	7	8	9	7	8	9	μV/e ⁻	
Dark current*10	Non-MPP operation	DS	-	50	300	-	100	600	ke ⁻ /pixel/s
	MPP operation		-	4	16	-	8	32	
Readout noise*11	Nr	-	30	45	-	30	45	e ⁻ rms	
Dynamic range*12	DR	-	6670	-	-	6670	-	-	
Spectral response range	λ	-	200 to 1100	-	-	200 to 1100	-	nm	
Photo response non-uniformity*13, *14	PRNU	-	±3	±10	-	±3	±10	%	
Image lag*13	L	-	0.1	1	-	0.1	1	%	

*10: Dark current is reduced to half for every 5 to 7 °C decrease in temperature.

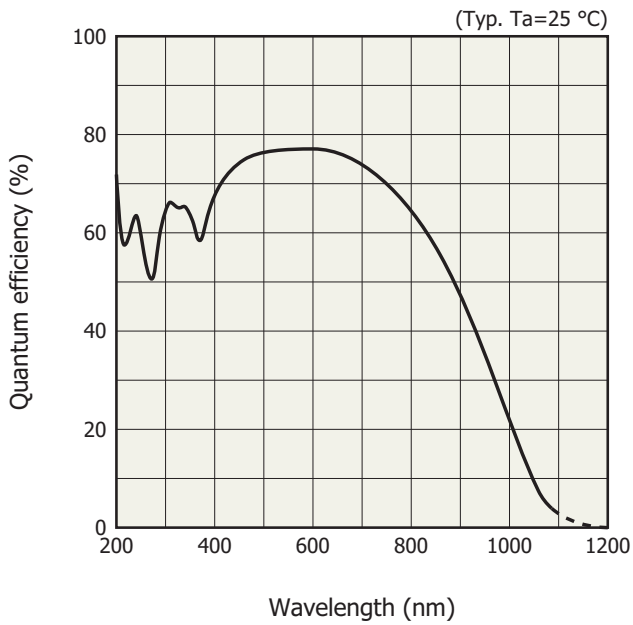
*11: Readout frequency is 2 MHz

*12: Dynamic range (DR) = Full well capacity / Readout noise

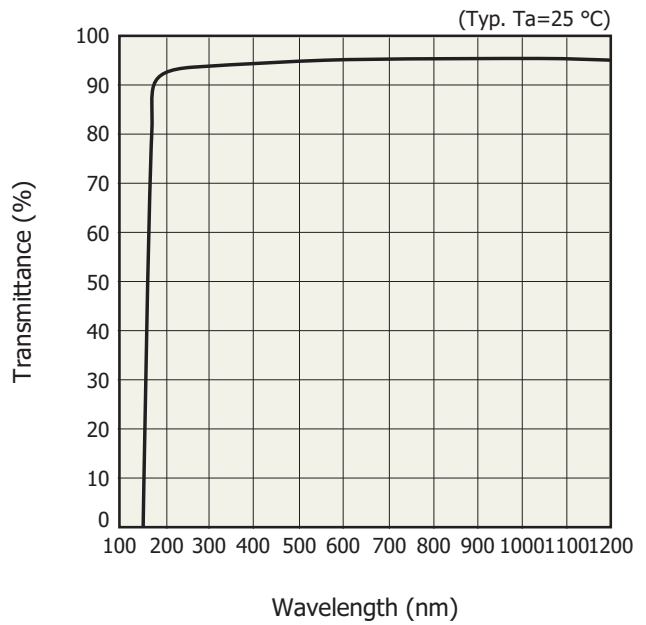
*13: Measured at one-half of the saturation output (full well capacity) using LED light (peak emission wavelength: 660 nm)

*14: Photo response non-uniformity = $\frac{\text{Fixed pattern noise (peak to peak)}}{\text{Signal}} \times 100$ [%]

Spectral response (without window)*15



Spectral transmittance characteristic of window material



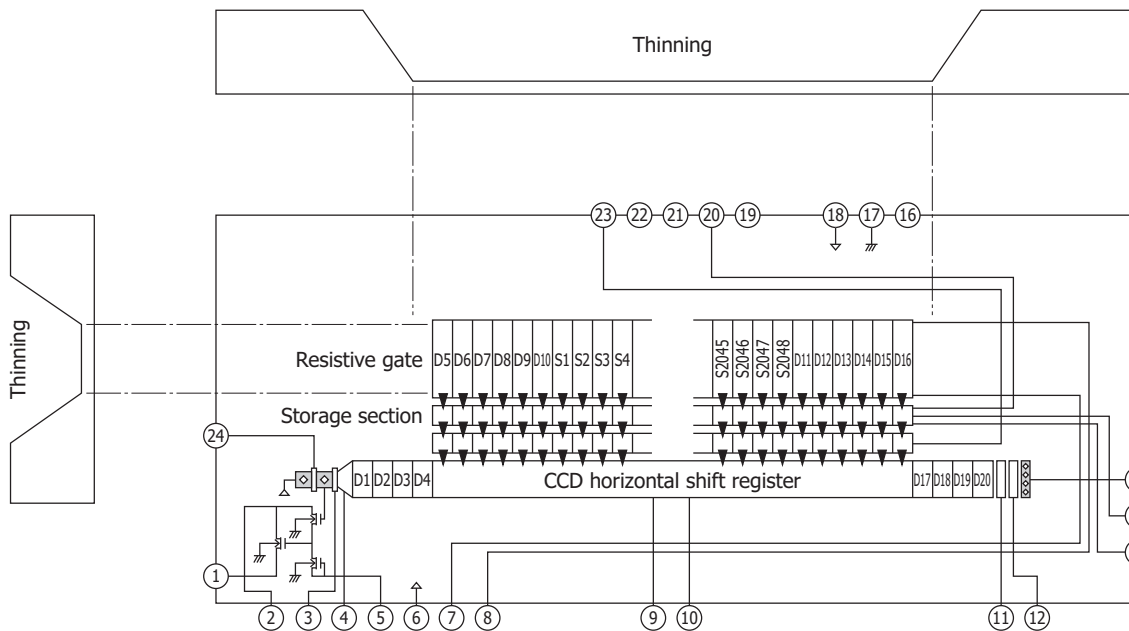
*15: Spectral response with quartz glass is decreased according to the spectral transmittance characteristic of window material.

Window material

Type No.	Window material
S11155-2048	Quartz glass*16 (option: window-less)
S11156-2048	

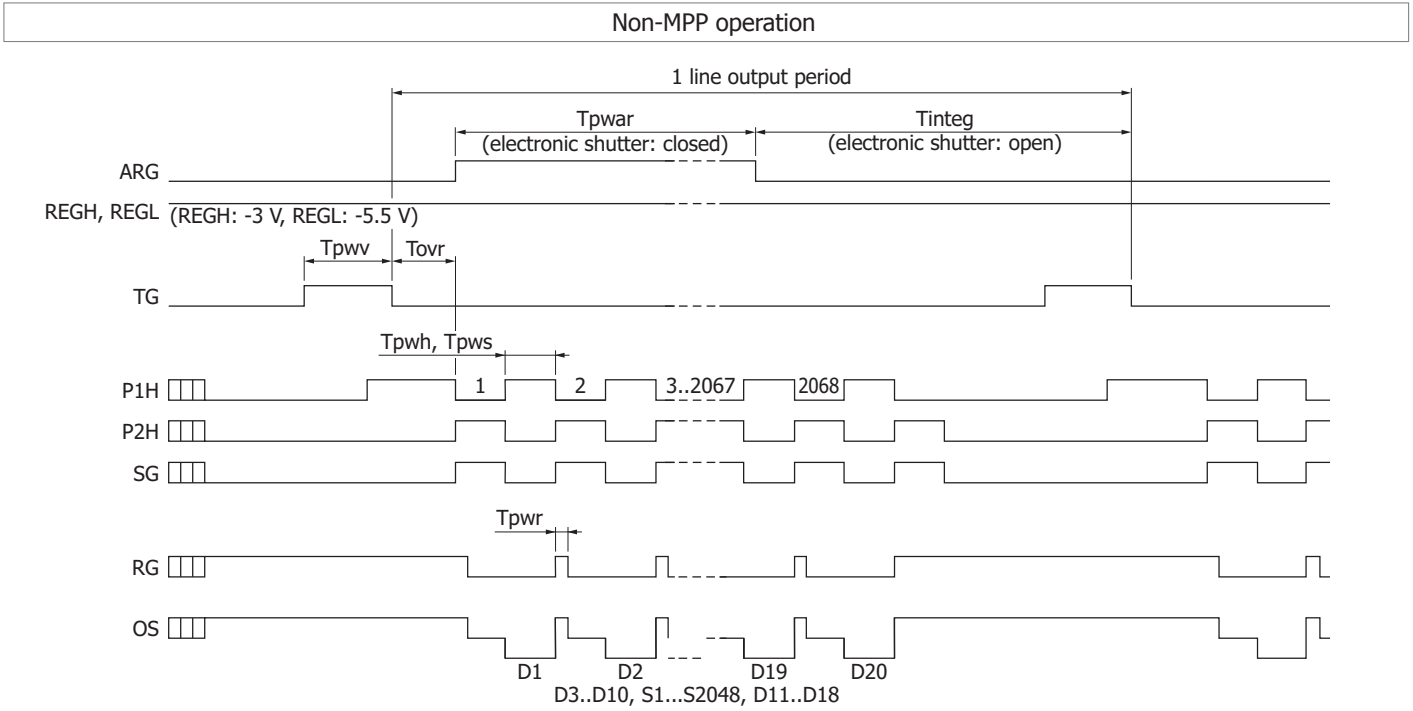
*16: Resin sealing

Device structure (conceptual drawing of top view in dimensional outline)



KMPDC0339EB

Timing chart

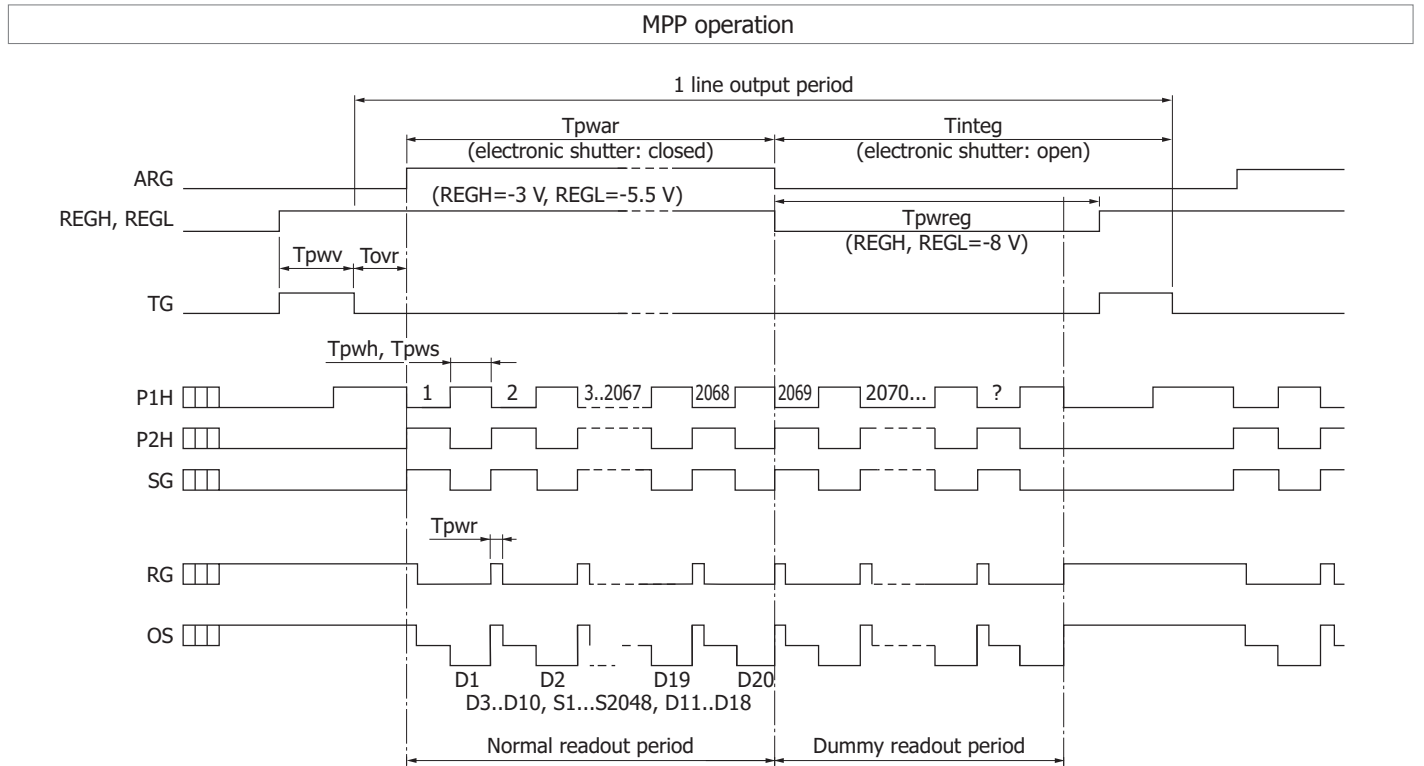


KMPDC0340EB

Parameter		Symbol	Min.	Typ.	Max.	Unit
ARG	Pulse width	Tpwar	1	-	-	μs
	Rise and fall times	Tprar, Tpfar	200	-	-	ns
TG	Pulse width	Tpww	30	-	-	μs
	Rise and fall time	Tprv, Tpfv	20	-	-	ns
P1H, P2H*17	Pulse width	Tpwh	50	100	-	ns
	Rise and fall time	Tprh, Tpfh	10	-	-	ns
	Duty ratio	-	40	50	60	%
SG	Pulse width	Tpws	50	100	-	ns
	Rise and fall time	Tprs, Tpfs	10	-	-	ns
	Duty ratio	-	40	50	60	%
RG	Pulse width	Tpwr	5	15	-	ns
	Rise and fall time	Tprr, Tpfr	5	-	-	ns
TG - P1H	Overlap time	Tovr	1	2	-	μs
Integration time		Tinteg	30	-	-	μs

*17: Symmetrical clock pulses should be overlapped at 50% of maximum amplitude.

Timing chart



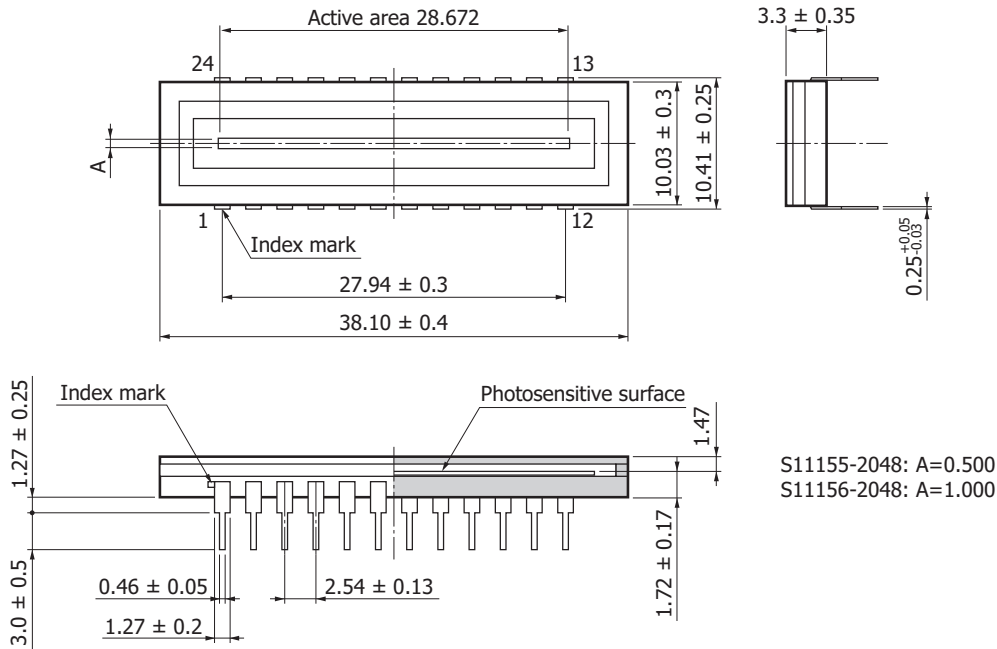
KMPDC0347EC

Parameter		Symbol	Min.	Typ.	Max.	Unit
ARG	Pulse width	T_{pwar}	*18	-	-	μs
	Rise and fall times	T_{prar}, T_{pfar}	200	-	-	ns
REGH, REGL	Pulse width	T_{pwreg}	-	$T_{integ} - T_{pww}$	-	μs
	Rise and fall times	T_{prreg}, T_{pfrg}	100	-	-	ns
TG	Pulse width	T_{pww}	30	-	-	μs
	Rise and fall times	T_{prv}, T_{pfv}	20	-	-	ns
P1H, P2H*19	Pulse width	T_{pwh}	50	100	-	ns
	Rise and fall times	T_{prh}, T_{pfh}	10	-	-	ns
	Duty ratio	-	40	50	60	%
SG	Pulse width	T_{pws}	50	100	-	ns
	Rise and fall times	T_{prs}, T_{pfs}	10	-	-	ns
	Duty ratio	-	40	50	60	%
RG	Pulse width	T_{pwr}	5	15	-	ns
	Rise and fall times	T_{prr}, T_{pfr}	5	-	-	ns
TG - P1H	Overlap time	T_{ovr}	1	2	-	μs
Integration time		T_{integ}	30	-	-	μs

*18: The Min. value of T_{pwar} is equal to the normal readout period.

*19: Symmetrical clock pulses should be overlapped at 50% of maximum amplitude.

Dimensional outline (unit: mm)



KMPDA0262EB

Pin connections

Pin no.	Symbol	Function	Remark (standard operation)
1	OS	Output transistor source	$R_L=2.2\text{ k}\Omega$
2	OD	Output transistor drain	+15 V
3	OG	Output gate	+5 V
4	SG	Summing gate	Same pulse as P2H
5	Vret	Output amplifier return	+1 V
6	RD	Reset drain	+15 V
7	REGL	Resistive gate (low)	-5.5 V (Non-MPP operation)
8	REGH	Resistive gate (high)	-3 V (Non-MPP operation)
9	P2H	CCD horizontal register clock-2	
10	P1H	CCD horizontal register clock-1	
11	IG2H	Test point (horizontal input gate-2)	-8 V
12	IG1H	Test point (horizontal input gate-1)	-8 V
13	ARG	All reset gate	
14	ARD	All reset drain	+12 V
15	ISH	Test point (horizontal input source)	Connect to RD
16	-		
17	SS	Substrate	GND
18	RD	Reset drain	+15 V
19	-		
20	STG	Storage gate	0 V
21	-		
22	-		
23	TG	Transfer gate	
24	RG	Reset gate	

Related information

http://jp.hamamatsu.com/sp/ssd/CCD_e.html

- Characteristics and use of resistive gate type CCD linear image sensors with electronic shutter

Driver circuits for CCD linear image sensor (S11155-2048, S11156-2048) C11165 [sold separately]

The C11165 is a driver circuit designed for HAMAMATSU CCD linear image sensors S11155-2048, S11156-2048. The C11165 can be used in spectrometer when combined with the CCD linear image sensor.

Features

- Built-in 16-bit A/D converter
- Interface of computer: USB 2.0
- Operates by DC+5 V



Information furnished by HAMAMATSU is believed to be reliable. However, no responsibility is assumed for possible inaccuracies or omissions. Specifications are subject to change without notice. No patent rights are granted to any of the circuits described herein. Type numbers of products listed in the specification sheets or supplied as samples may have a suffix "(X)" which means tentative specifications or a suffix "(Z)" which means developmental specifications. ©2010 Hamamatsu Photonics K.K.

HAMAMATSU

www.hamamatsu.com

HAMAMATSU PHOTONICS K.K., Solid State Division
 1126-1 Ichino-cho, Higashi-ku, Hamamatsu City, 435-8558 Japan, Telephone: (81) 53-434-3311, Fax: (81) 53-434-5184
 U.S.A.: Hamamatsu Corporation: 360 Foothill Road, P.O.Box 6910, Bridgewater, N.J. 08807-0910, U.S.A., Telephone: (1) 908-231-0960, Fax: (1) 908-231-1218
 Germany: Hamamatsu Photonics Deutschland GmbH: Arzbergerstr. 10, D-82211 Herrsching am Ammersee, Germany, Telephone: (49) 8152-375-0, Fax: (49) 8152-265-8
 France: Hamamatsu Photonics France S.A.R.L.: 19, Rue du Saule Trapu, Parc du Moulin de Massy, 91882 Massy Cedex, France, Telephone: 33-(1) 69 53 71 00, Fax: 33-(1) 69 53 71 10
 United Kingdom: Hamamatsu Photonics UK Limited: 2 Howard Court, 10 Tewin Road, Welwyn Garden City, Hertfordshire AL7 1BW, United Kingdom, Telephone: (44) 1707-294888, Fax: (44) 1707-325777
 North Europe: Hamamatsu Photonics Norden AB: Smidesvägen 12, SE-171 41 Solna, Sweden, Telephone: (46) 8-509-031-00, Fax: (46) 8-509-031-01
 Italy: Hamamatsu Photonics Italia S.R.L.: Strada della Moia, 1 int. 6, 20020 Arese, (Milano), Italy, Telephone: (39) 02-935-81-733, Fax: (39) 02-935-81-741